

Electronic Patent Application Fee Transmittal

Application Number:	10585461			
Filing Date:				
Title of Invention:	Circuit connection material, film-shaped circuit connection material using the same, circuit member connection structure, and manufacturing method thereof			
First Named Inventor/Applicant Name:	Jun Taketatsu			
Filer:	William Ivan Solomon/Ricardo Perez			
Attorney Docket Number:	1303.46354X00			
Filed as Large Entity				
U.S. National Stage under 35 USC 371 Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Oath/decl > 30 months from priority date	1617	1	130	130
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Extension-of-Time:				

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Total in USD (\$)				130